

SILICON GATE BiCMOS

32,768 WORD x 9 BIT BiCMOS STATIC RAM

Description

The TC55B329P/J is a 294,912 bit high speed BiCMOS static random access memory organized as 32,768 words by 9 bits and operated from a single 5V supply. Toshiba's BiCMOS technology and advanced circuit design enable high speed operation.

The TC55B329P/J features low power dissipation when the device is deselected using chip enable ($\overline{CE1}$, $\overline{CE2}$) and has an output enable input (\overline{OE}) for fast memory access.

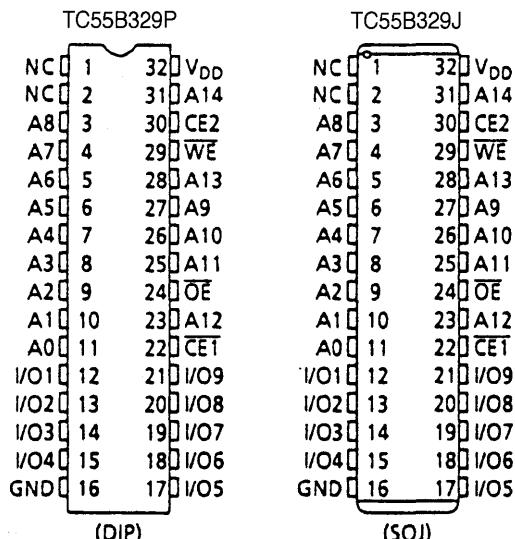
The TC55B329P/J is suitable for use in high speed applications such as cache memory and high speed storage. All inputs and outputs are TTL compatible.

The TC55B329P/J is available in a 300mil width, 32-pin DIP and SOJ suitable for high density surface assembly.

Features

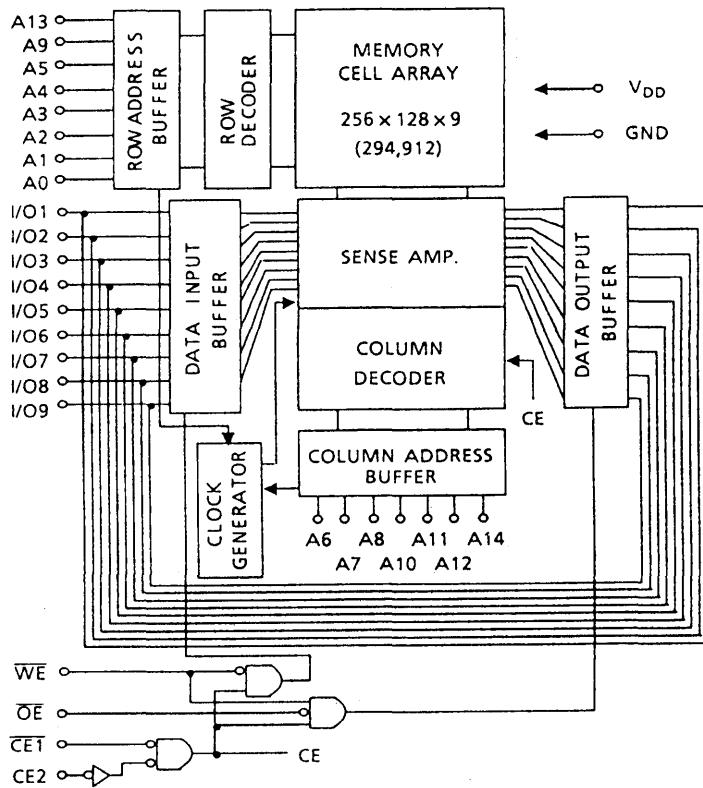
- Fast access time
 - TC55B329P/J-10 10ns (max.)
 - TC55B329P/J-12 12ns (max.)
- Low power dissipation
 - Operation:
 - TC55B329P/J-10 170mA (max.)
 - TC55B329P/J-12 170mA (max.)
 - Standby: 15mA (max.)
 - Single 5V power supply: $5V \pm 10\%$
- Fully static operation
- Inputs and outputs TTL compatible
- Output buffer control: \overline{OE}
- Package:
 - TC55B329P: DIP32-P-300
 - TC55B329J: SOJ32-P-300

Pin Connection (Top View)



Pin Names

| | |
|-----------------|---------------------|
| A0 ~ A14 | Address Inputs |
| I/O1 ~ I/O9 | Data Inputs/Outputs |
| CE1, CE2 | Chip Enable Inputs |
| WE | Write Enable Input |
| OE | Output Enable Input |
| V _{DD} | Power (+5V) |
| GND | Ground |
| NC | No Connection |

Block Diagram**Operating Mode**

| MODE | PIN | CE1 | CE2 | OE | WE | I/O1 ~ I/O9 | POWER |
|----------------|-----|-----|-----|----|----|----------------|-----------|
| Read | | L | H | L | H | Output | I_{DDO} |
| Write | | L | H | * | L | Input | I_{DDO} |
| Output Disable | | L | H | H | H | High Impedance | I_{DDO} |
| Standby | | H | * | * | * | High Impedance | I_{DDS} |
| | | * | L | * | * | High Impedance | I_{DDS} |

*H or L

Maximum Ratings

| SYMBOL | ITEM | RATING | UNIT |
|--------------|------------------------------|------------------------|----------|
| V_{DD} | Power Supply Voltage | -0.5 ~ 7.0 | V |
| V_{IN} | Input Voltage | -2.0 ~ 7.0 | V |
| $V_{I/O}$ | Input/Output Voltage | -0.5* ~ $V_{DD} + 0.5$ | V |
| P_D | Power Dissipation | 1.0 | W |
| T_{SOLDER} | Soldering Temperature • Time | 260 • 10 | °C • sec |
| T_{STRG} | Storage Temperature | -65 ~ 150 | °C |
| T_{OPR} | Operating Temperature | -10 ~ 85 | °C |

*-3V with a pulse width of 10ns

DC Recommended Operating Conditions

| SYMBOL | PARAMETER | MIN. | TYP. | MAX. | UNIT |
|----------|----------------------|-------|------|----------------|------|
| V_{DD} | Power Supply Voltage | 4.5 | 5.0 | 5.5 | V |
| V_{IH} | Input High Voltage | 2.2 | - | $V_{DD} + 0.5$ | V |
| V_{IL} | Input Low Voltage | -0.5* | - | 0.8 | V |

* -3V with a pulse width of 10ns

DC Characteristics ($T_a = 0 \sim 70^\circ C$, $V_{DD} = 5V \pm 10\%$)

| SYMBOL | PARAMETER | TEST CONDITION | MIN. | TYP. | MAX. | UNIT |
|------------|------------------------|--|------|------|----------|---------|
| I_{LI} | Input Leakage Current | $V_{IN} = 0 \sim V_{DD}$ | - | - | ± 10 | μA |
| I_{LO} | Output Leakage Current | $\overline{CE1} = V_{IH}$ or $CE2 = V_{IL}$ or $\overline{OE} = V_{IH}$ or $\overline{WE} = V_{IL}$, $V_{OUT} = 0 \sim V_{DD}$ | - | - | ± 10 | μA |
| I_{OH} | Output High Current | $V_{OH} = 2.4V$ | -4 | - | - | mA |
| I_{OL} | Output Low Current | $V_{OL} = 0.4V$ | 8 | - | - | mA |
| I_{DDO} | Operating Current | $t_{cycle} = \text{Min cycle}$, $\overline{CE1} = V_{IL}$ and $CE2 = V_{IH}$ Other Inputs = V_{IH}/V_{IL} , $I_{OUT} = 0mA$ | - | - | 170 | mA |
| I_{DDS1} | Standby Current | $\overline{CE1} = V_{IH}$ or $CE2 = V_{IL}$ Other Inputs = V_{IH}/V_{IL} | - | - | 30 | mA |
| I_{DDS2} | | $\overline{CE1} = V_{DD} - 0.2V$ or $CE2 = 0.2V$ Other Inputs = $V_{DD} - 0.2V$ or $0.2V$ | - | - | 15 | |

Capacitance* ($T_a = 25^\circ C$, $f = 1.0MHz$)

| SYMBOL | PARAMETER | TEST CONDITION | MAX. | UNIT |
|-----------|--------------------------|-----------------|------|------|
| C_{IN} | Input Capacitance | $V_{IN} = GND$ | 6 | pF |
| $C_{I/O}$ | Input/Output Capacitance | $V_{I/O} = GND$ | 8 | pF |

*This parameter is periodically sampled and is not 100% tested.

AC Characteristics (Ta = 0 ~ 70°C⁽¹⁾, V_{DD} = 5V±10%)**Read Cycle**

| SYMBOL | PARAMETER | TC55B329P/J-10 | | TC55B329P/J-12 | | UNIT |
|------------------|---|----------------|------|----------------|------|------|
| | | MIN. | MAX. | MIN. | MAX. | |
| t _{RC} | Read Cycle Time | 10 | — | 12 | — | ns |
| t _{ACC} | Address Access Time | — | 10 | — | 12 | |
| t _{CO1} | CE1 Access Time | — | 10 | — | 12 | |
| t _{CO2} | CE2 Access Time | — | 10 | — | 12 | |
| t _{OE} | OE Access Time | — | 5 | — | 6 | |
| t _{OH} | Output Data Hold Time from Address Change | 3 | — | 3 | — | |
| t _{COE} | Output Enable Time from CE1 or CE2 | 3 | — | 3 | — | |
| t _{COD} | Output Disable Time from CE1 or CE2 | — | 5 | — | 6 | |
| t _{OEE} | Output Enable Time from OE | 1 | — | 1 | — | |
| t _{ODO} | Output Disable Time from OE | — | 5 | — | 6 | |
| t _{PU} | Chip Selection to Power Up Time | 0 | — | 0 | — | |
| t _{PD} | Chip Deselection to Power Down Time | — | 10 | — | 12 | |

Write Cycle

| SYMBOL | PARAMETER | TC55B329P/J-10 | | TC55B329P/J-12 | | UNIT |
|------------------|-------------------------------|----------------|------|----------------|------|------|
| | | MIN. | MAX. | MIN. | MAX. | |
| t _{WC} | Write Cycle Time | 10 | — | 12 | — | ns |
| t _{cw} | Chip Enable to End of Write | 7 | — | 8 | — | |
| t _{AS} | Address Setup Time | 0 | — | 0 | — | |
| t _{AW} | Address Valid to End of Write | 7 | — | 8 | — | |
| t _{WP} | Write Pulse Width | 6 | — | 7 | — | |
| t _{WR} | Write Recovery Time | 1 | — | 1 | — | |
| t _{DS} | Data Setup Time | 6 | — | 7 | — | |
| t _{DH} | Data Hold Time | 0 | — | 0 | — | |
| t _{OEW} | Output Enable Time from WE | 1 | — | 1 | — | |
| t _{ODW} | Output Disable Time from WE | — | 5 | — | 6 | |

AC Test Conditions

| | |
|--|-----------|
| Input Pulse Levels | 3.0V/0.0V |
| Input Pulse Rise and Fall Time | 3ns |
| Input Timing Measurement Reference Levels | 1.5V |
| Output Timing Measurement Reference Levels | 1.5V |
| Output Load | Fig. 1 |

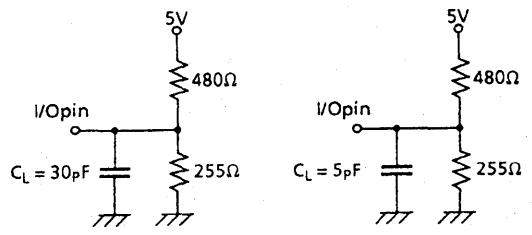
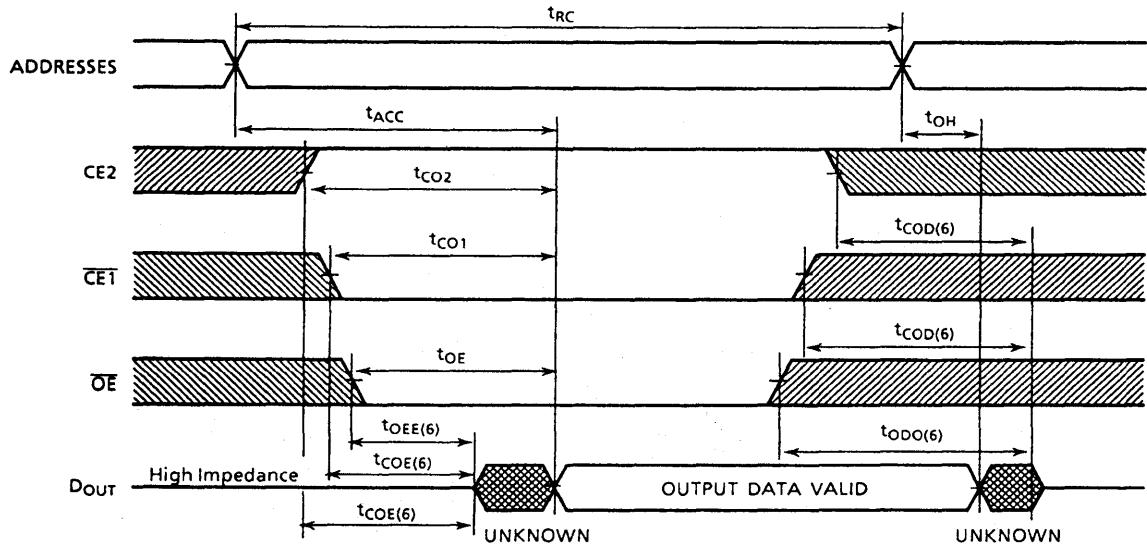
(For t_{COE}, t_{OEE}, t_{COD}, t_{ODO}, t_{OEW} and t_{ODW})

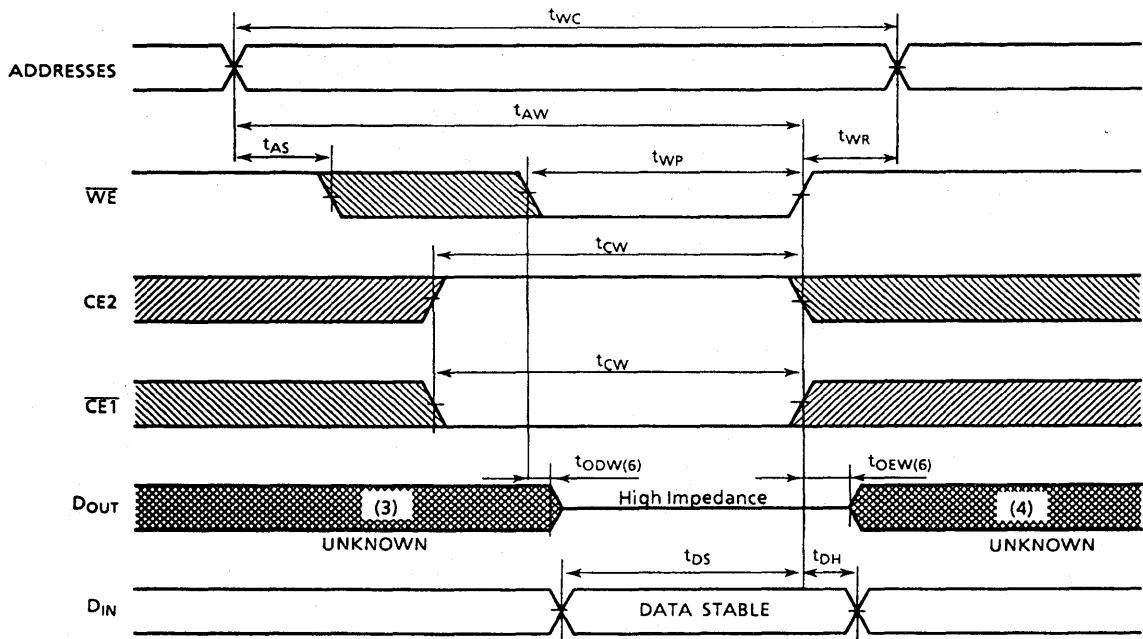
Figure 1.

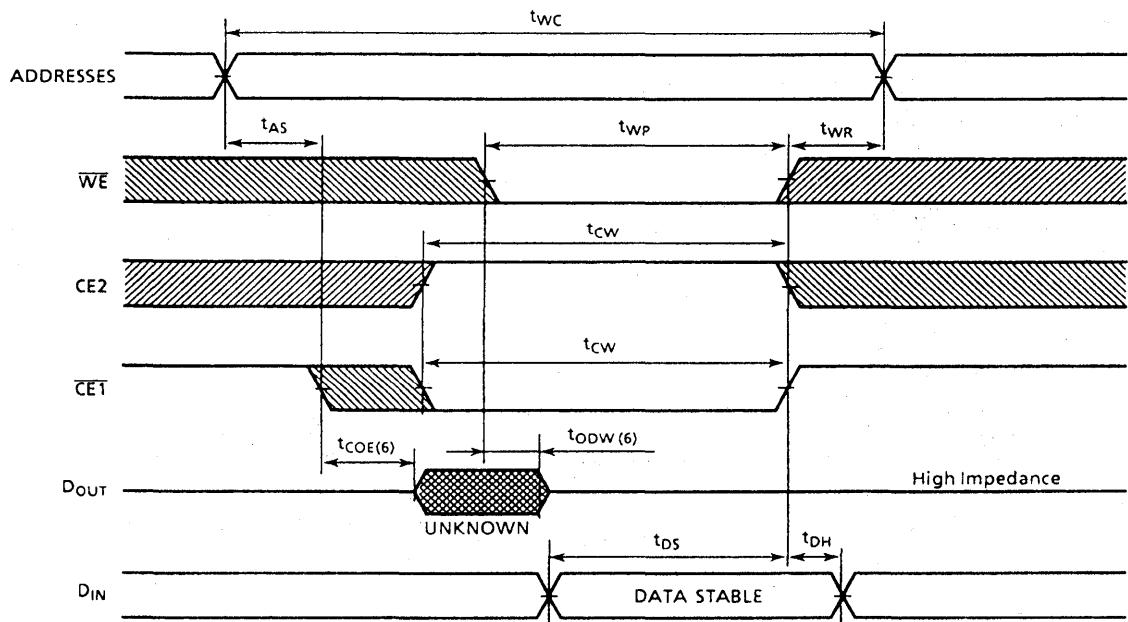
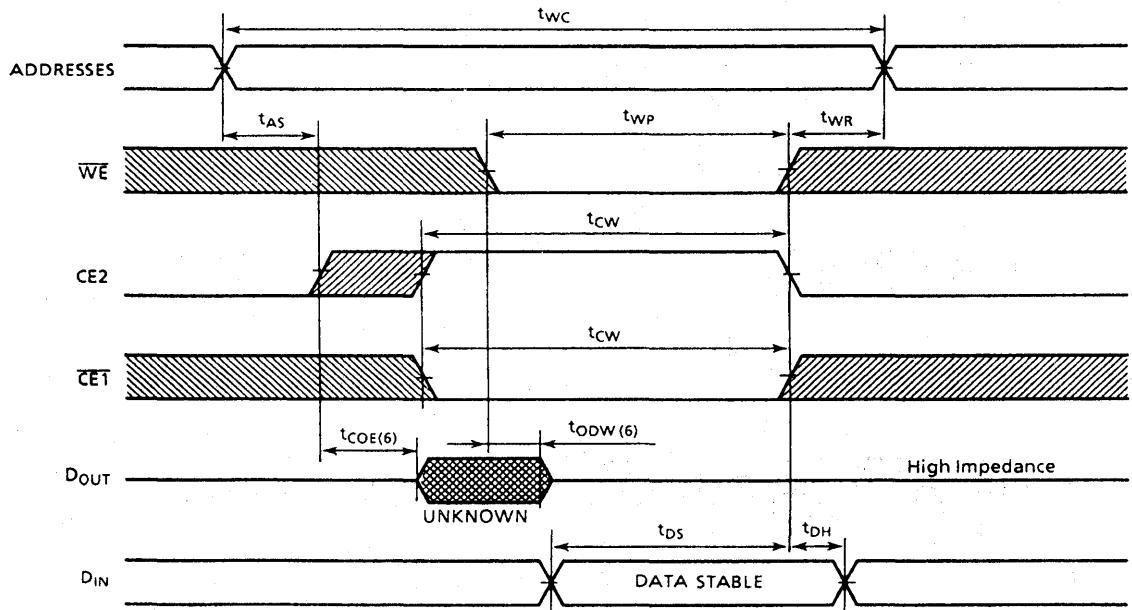
Timing Waveforms

Read Cycle (2)



Write Cycle 1 (5) (\overline{WE} Controlled Write)



Write Cycle 2⁽⁵⁾ (CE1 Controlled Write)Write Cycle 3⁽⁵⁾ (CE2 Controlled Write)

Notes:

1. The operating temperature (T_a) is guaranteed with transverse air flow exceeding 400 linear feet per minute.
2. \overline{WE} is high for read cycles.
3. If the $\overline{CE1}$ low transition or $CE2$ high transition occurs coincident with or after the \overline{WE} low transition, outputs remain in a high impedance state.
4. If the $\overline{CE1}$ high transition or $CE2$ low transition occurs coincident with or prior to the \overline{WE} high transition, outputs remain in a high impedance state.
5. If \overline{OE} is high during a write cycle, the outputs are in a high impedance state during this period.
6. The following parameters are measured using the load shown in Fig. 1.
(A) $t_{COE}, t_{OEE}, t_{OWE} \dots$ Output Enable Time
(B) $t_{COD}, t_{ODO}, t_{ODW} \dots$ Output Disable Time

